

## ABSTRACT

A through electrode substrate includes: a glass substrate including a first surface, a second surface located on a side opposite to the first surface, and a first through hole and a second through hole extending from the first surface to the second surface; a through electrode located in the first through hole; a resin member located in the second through hole; and a wiring layer located between the glass substrate and a semiconductor element. The first through hole includes a first opening that is open at the first surface of the glass substrate and a second opening that is open at the second surface of the glass substrate. The second through hole includes a third opening that is open at the first surface of the glass substrate and a fourth opening that is open at the second surface of the glass substrate. The through electrode closes the first through hole between the first opening and the second opening. The resin member continuously extends in the second through hole from the third opening to the fourth opening.